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IEC PAS 61249-8-5

Edition 1.0 2014-06

PUBLICLY AVAILABLE SPECIFICATION

PRE-STANDARD

Qualification and performance specification of permanent solder mask and flexible cover materials

INTERNATIONAL
ELECTROTECHNICAL
COMMISSION

PRICE CODE

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ICS 31.180

ISBN 978-2-8322-1633-0

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QUALIFICATION AND PERFORMANCE SPECIFICATION OF PERMANENT SOLDER MASK AND FLEXIBLE COVER MATERIALS

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Draft PAS	Report on voting
91/1157/PAS	91/1174/RVD

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IPC-SM-840E

2010 - December

Qualification and Performance Specification of Permanent Solder Mask and Flexible Cover Materials

Supersedes IPC-SM-840D

April 2007

A standard developed by IPC

Association Connecting Electronics Industries



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IPC-SM-840E

Qualification and Performance Specification of Permanent Solder Mask and Flexible Cover Materials

Developed by the Solder Mask Performance Task Group (5-33B) of the Cleaning and Coating Committee (5-30) and the Covercoat Materials Task Group (D-13B) of the Flexible Circuits Committee (D-10) of IPC

Supersedes:

IPC-SM-840D - April 2007
IPC-SM-840C -
 Amendment 1 - June 2000
IPC-SM-840C - January 1995
IPC-SM-840B - May 1988
IPC-SM-840A - July 1983
IPC-SM-840 - November 1977

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Acknowledgment

Any document involving a complex technology draws material from a vast number of sources. While the principal members of the Solder Mask Performance Task Group (5-33B) of the Cleaning and Coating Committee (5-30) and the Covercoat Materials Task Group (D-13B) of the Flexible Circuits Committee (D-10) are shown below, it is not possible to include all of those who assisted in the evolution of this standard. To each of them, the members of IPC extend their gratitude.

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Qualification and Performance Specification of Permanent Solder Mask and Flexible Cover Materials

1 SCOPE AND DESIGNATION

1.1 Scope This specification **shall** define the criteria for and method of obtaining the maximum information about and confidence in cured permanent solder mask and cover material under evaluation with the minimum of test redundancy.

This specification **shall** establish the requirements for:

- The evaluation of solder mask and cover materials
- The conformance of solder mask and cover material properties
- The qualification of the solder mask and cover material via the appropriate test substrate
- The qualification assessment of the solder mask and cover material in conjunction with the production printed board process